

HSL-DI16DO16-DB-NN/-NP/-PN/-PP

16-CH Discrete Input 16-CH Discrete Output Daughter Board Modules



Specifications

Slave ID Consumption	1
Interface	NN: for NPN sinking type sensor input or dry contact and NPN sinking type output NP: for NPN sinking type sensor input or dry contact and PNP sourcing type output PN: for PNP sourcing type sensor input or wet contact and NPN sinking type output PP: for PNP sourcing type sensor input or wet contact and PNP sourcing type output
Photo Couple Isolation Voltage	2500 VRMS
Input Impedance	4.7 KΩ
Input Current	±10 mA (max.), ±12.5 mA (peak)
Input Voltage	±40 V (max.)
Output Switching Capacity	Single channel 400 mA; Full channels 50 mA at 100% duty cycle
LED Indicator	Power, Link and I/O status
Power Supply	22 V to 26 VDC
Operating Temperature	0°C to +60°C
Storage Temperature	-20°C to +80°C
Power Consumption	1.8 W



HSL-DI32-DB-N/-P

32-CH Discrete Input Daughter Board Modules



Specifications

Slave ID Consumption	2 consecutive from odd
Interface	N: for NPN sinking type sensor input or dry contact P: for PNP sourcing type sensor input or wet contact
Photo Couple Isolation Voltage	2500 VRMS
LED Indicator	Power, Link and Input status
Power Supply	22 V to 26 VDC
Operating Temperature	0°C to +60°C
Storage Temperature	-20°C to +80°C
Power Consumption	1.8 W
CE Certificate	Ready
Input Impedance	4.7 KΩ
Input Current	±10 mA (max.), ±12.5 mA (peak)
Input Voltage	±40 V (max.)



HSL-DO32-DB-N/-P

32-CH Discrete Output Daughter Board Modules



Specifications

Slave ID Consumption	2 consecutive from odd
Interface	N: for NPN sinking type sensor input or dry contact P: for PNP sourcing type sensor input or wet contact
Photo Couple Isolation Voltage	2500 VRMS
LED Indicator	Power, Link and Input status
Power Supply	22 V to 26 VDC
Operating Temperature	0°C to +60°C
Storage Temperature	-20°C to +80°C
Power Consumption	1.8 W
CE Certificate	Ready
Response Time	ON → OFF: 180 μs, OFF → ON: 1.2 μs
Switch Capacity	Single channel 500 mA; Full channels 50 mA at 100% duty cycle



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cPCI & Industrial Computers